Title (en)

APPARATUS AND METHOD TO PROVIDE A THERMAL PARAMETER REPORT FOR A MULTI-CHIP PACKAGE

Title (de)

VORRICHTUNG UND VERFAHREN ZUR BEREITSTELLUNG EINES WÄRMEPARAMETERBERICHTS FÜR EINE MULTICHIP-PACKUNG

Title (fr)

APPAREIL ET PROCÉDÉ POUR FOURNIR UN RAPPORT DE PARAMÈTRE THERMIQUE POUR UN BOÎTIER MULTI-PUCE

Publication

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Application

EP 15873930 A 20151119

Priority

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- US 2015061517 W 20151119

Abstract (en)

[origin: US2016179158A1] In an embodiment, a processor includes at least one core and power management logic. The power management logic is to receive temperature data from a plurality of dies within a package that includes the processor, and determine a smallest temperature control margin of a plurality of temperature control margins. Each temperature control margin is to be determined based on a respective thermal control temperature associated with the die and also based on respective temperature data associated with the die. The power management logic is also to generate a thermal report that is to include the smallest temperature control margin, and to store the thermal report. Other embodiments are described and claimed.

IPC 8 full level

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CPC (source: CN EP US)

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DOCDB simple family (application)

US 201514852859 A 20150914; CN 201580063797 A 20151119; CN 202011188397 A 20151119; CN 202111491867 A 20151119; DE 202015009867 U 20151119; EP 15873930 A 20151119; EP 20203849 A 20151119; TW 104138328 A 20151119; TW 106116733 A 20151119; US 2015061517 W 20151119; US 202016898603 A 20200611